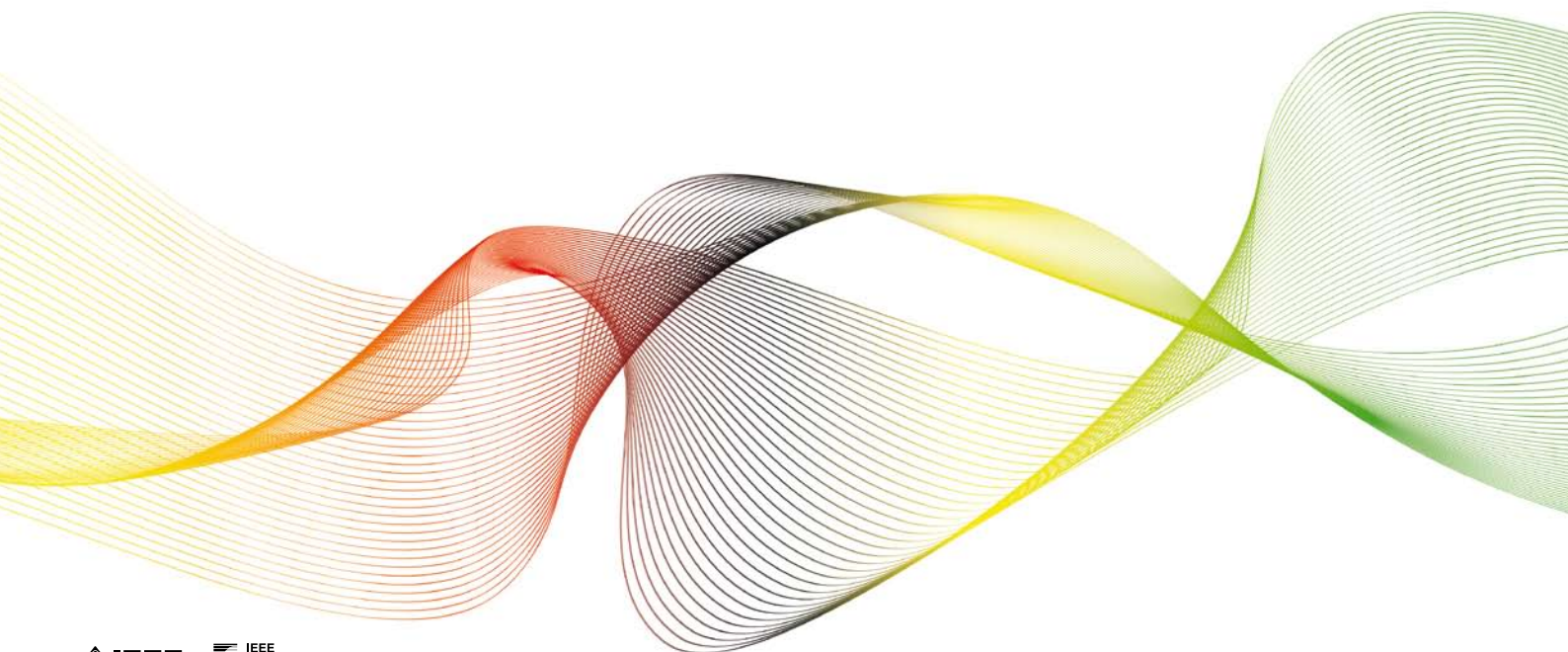
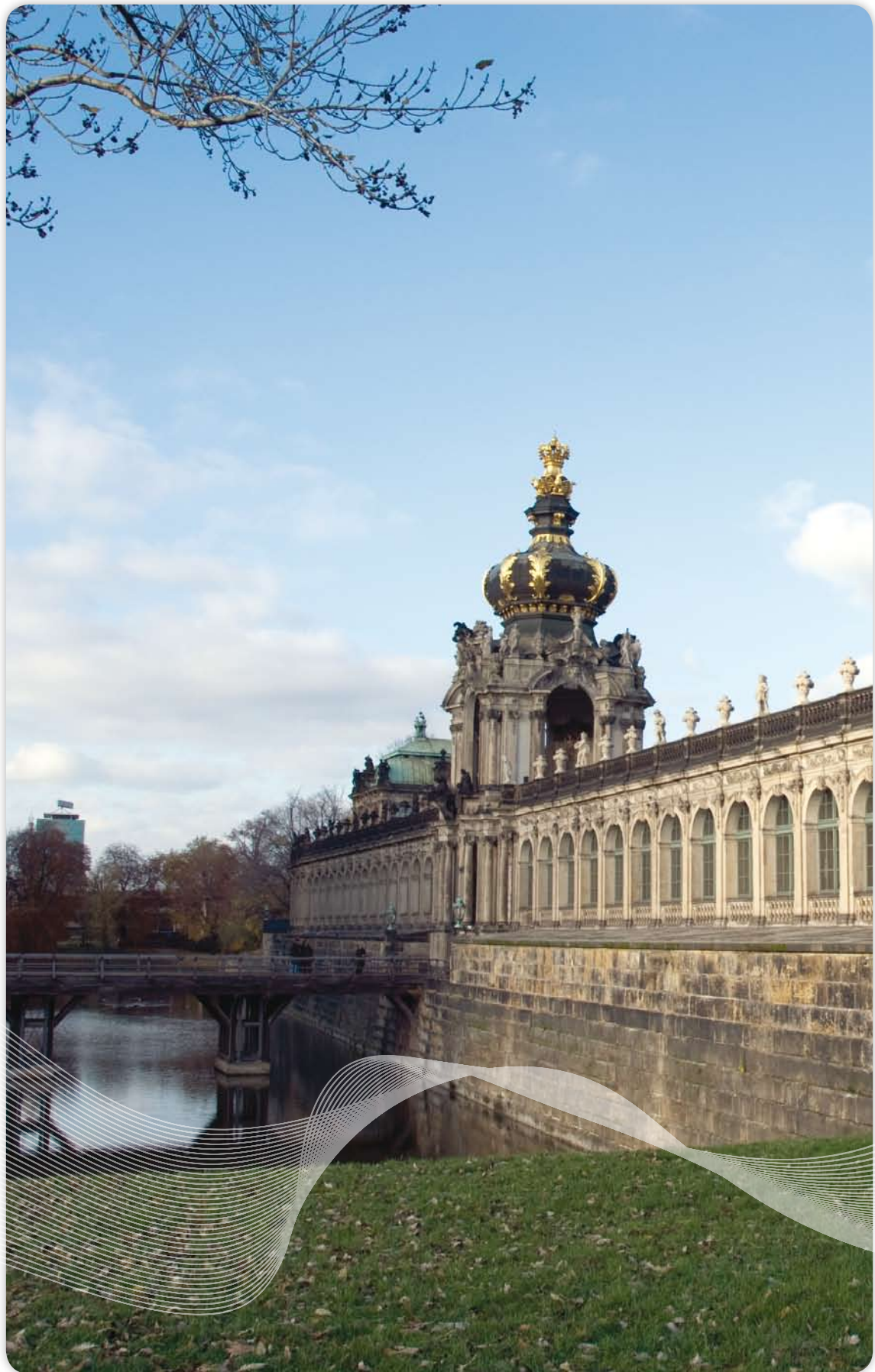




IEEE ICC 2009 | June 14 – 18 Dresden, Germany

A Tradition of Innovation.





IEEE International Conference on Communications at a glance

The international event on communications

- The conference brings together experts from the worldwide communications industry and research communities
- The conference focuses on a high-quality technical programme and plenary sessions
- Recent advances in all fields related to communications will be presented, including key technologies, standardization, demonstrations, conference talks, panel discussions.

Programme

- Sun, June 14, 2009: tutorials and a welcome reception
- Mon-Wed, June 15-17: three full conference days
- The technical programme will be complemented by a series of workshops, to be held on June 18, 2009
- The conference dinner will take place in the historic downtown of Dresden on Tuesday, June 16.
- Activities around the conference include cultural highlights (e.g. Semper Opera), and outdoor activities (e.g. hiking in Saxon Switzerland)

Expected participation

- Based on previous years' figures we expect about 1500 participants from all over the world
- About 30 exhibition booths give enough space for presentations and demonstrations of recent advances in research and development

History

Since 1965
2002 – New York, USA
2003 – Alaska, USA
2004 – Paris, France
2005 – Seoul, Korea
2006 – Istanbul, Turkey
2007 – Glasgow, Scotland
2008 – Beijing, China
2009 – Dresden, Germany

Dresden - Location

- Halfway between Berlin and Prague
- 510,000+ people
- Airport with frequent connections to major European hubs



“Silicon Saxony”

No.1 semiconductor site in Europe, No.5 on the planet

Currently 42000 employees in semiconductors and information & communications technologies. Here are the largest players:

- AMD (2 x 12" processor fab)
- Applied Materials
- ATMEL
- Infineon (1 x 8" logic fabs)
- NXP Semiconductors (Systemonic)
- Qimonda (1 x 12" DRAM fab, 1 x 8" DRAM)
- Siltronic 6" & 12" wafer production
- Toppan / Dupont Photomasks
- X-Fab, 6" fab
- ZMD, fab-less mixed signal ASIC design

Major R&D

- TU Dresden with 35000 students
- Fraunhofer with 11 institutes and 1200 employees
- Max Planck with 3 institutes and 600 employees
- Leibnitz Gesellschaft with 4 institutes and 2300 employees

Networks

- Silicon Saxony with 250 members and growing! www.silicon-saxony.net

Venue

International Congress Center Dresden (ICCD)

Historic inner city

The International Congress Center of Dresden lies in the heart of the historical city amongst its popular sights: the Semper Opera House, the Zwinger or the Frauenkirche.

The congress center offers a variety of conference rooms and facilities with variable capacity, allowing for a flexible and convenient arrangement of the venue.

A number of excellent transportation connections exist for anyone wishing to arrive in Dresden by motorway, railway or the airport.

The ICCD opened in May 2004 together with to the Hotel “Maritim” located beside the conference center.





Why to Patronize

- The IEEE ICC is the global, world-class event to present the most recent results from research, development and standardization
- The IEEE ICC brings together industry leaders and scientists from around the globe to debate, discuss and learn about the technologies, business opportunities and new applications.
- Patrons enjoy extraordinary visibility with the powerful audience at the conference. There is no competition for time between conference sessions and networking receptions. The character of the event as a place where important ideas are exchanged is evident and continually reinforced throughout the event.
- The IEEE ICC attracts the “Who's Who” in communications, i.e., leading customers, operators, vendors, researchers, investors and press. Attendees mingle in a relaxed environment, and discuss the future of communications with those who are shaping it.
- Patrons gain access to research executives and directors of some of the world's leading R&D organizations and project representatives. The event's attendees are responsible for setting R&D and product development goals and have a considerable budget responsibility.
- Patrons enjoy an invitation to the special “VIP” welcome reception. Patrons, TPC members, and invited speakers will gather in one of Dresden's scenic spots for a unique discussion and networking event.
- The IEEE ICC has a long track record and an increasingly powerful, loyal audience. Since 1965 it has a reputation as “major communications event”.

How to Patronize

In short, patronizing the IEEE ICC represents a possibility to

- establish both relationships and partnerships,
- enhance your organization's reputation and profile,
- contact potential customers and employees.

Benefits go beyond just spreading the brand name.

Steps towards patronage

- Patronage packages:
 - We offer turnkey patronage packages described on the next pages
 - Choosing a package just requires filling in the corresponding data in the attached patronage agreement (Annex I remains as is in this case)
 - Send signed agreement to the contact details given on the last page
- Tailoring patronage solutions
 - We are open for ideas and negotiations that allow for tailoring the standard packages to your needs
 - In this case Annex I changed accordingly

Previous Patrons

ICC'07: Scottish Enterprise, Vodafone, Qualcomm, Picstel, Nokia Siemens Networks, Alcatel-Lucent

ICC'06: Turkcell, Alcatel, Turk Telekom, Siemens, Tübitak, Nokia, eKom, Telenity, Havelsan, HP, Karel, Cisco Systems, Ericsson

ICC'05: KT, Samsung Electronics, LG Electronics, SK Telecom, Cisco Systems, KTF

Patronage Packages

Diamond patronage – the premium package

Major benefits:

- Four full conference registrations including all social events
- Three invitations to the exclusive “VIP” welcome reception
- One full page advertisement in program; Additional advertisement of appropriate size on colored back cover of CD-ROM and program (size is up to the organizer); All advertisements must be provided by sponsor
- Logo displayed on program brochure (with other sponsors but visibly larger than Platinum sponsor); Logo must be provided by sponsor
- Your company name and the nature of your sponsorship listed on a display panel in the foyer area of the congress center
- Colored back cover of program and CD-ROM
- Company-flag in front of the venue (patron must provide a max. of 5 flags)
- Key note speech during conference (session is up to the conference organizer)
- Complimentary very large exhibition booth (size: either 2m x 12m or 4m x 6m)
- Patron’s material (to be provided by patron and approved by conference organizer) added to conference bag
- Acknowledgement by chairman during welcome reception and banquet dinner
- Participation in the press conference
- Right to provide a tutorial (session is up to the conference organizer)
- Automatically either patron of “Social Event” or “Lunch/Coffee Break” (as described later)

Any financial funding at € 60,000 or above

Platinum patronage

Major benefits:

- Three full conference registrations inclusive of social events
- Two invitations to the exclusive “VIP” welcome reception
- Full page advertisement in program by patron
- Logo displayed on program brochure (with other patrons but at larger size than Gold patron); Logo must be provided by patron
- Your company name and the nature of your patronage listed on a display panel in the foyer area of the ICC
- Company-flag in front of the venue (patron must provide a max. of 5 flags)
- Key note speech during conference (session is up to the conference organizer)
- Complimentary large exhibition booth (size: 2m x 6m)
- Patron’s material (to be provided by patron and approved by conference organizer) added to conference bag
- Acknowledgement by chairman during welcome reception and banquet dinner
- Participation in the press conference

Any financial funding at € 30,000 or above

Gold patronage

Major benefits:

- Two full conference registration inclusive social events
- One invitation to the exclusive "VIP" welcome reception
- Full page advertisement in program by patron
- Logo displayed on program brochure; Logo must be provided by patron
- Your company name and the nature of your patronage listed on a display panel in the foyer area of the ICC
- Complimentary medium exhibition booth (size: 2m x 3m)
- Acknowledgement by chairman during welcome reception

Any financial funding at € 15,000 or above

Silver patronage

Major benefits:

- One full conference registration inclusive of social events
- Half page advertisement in program, provided by patron
- Logo listed on program brochure; Logo must be provided by patron
- Additional conference booth (size: 2m x 3m) for 2k€ (500€ discount)

Any financial funding at € 5,000 or above

Banquet patronage

Major benefits:

- Full Gold patronage
- Additional 15-20 minute speech during banquet dinner

Any financial funding at € 20,000 or above

Lunch/coffee break patronage

Major benefits:

- Exclusive right to provide additional merchandising during lunch and coffee breaks (merchandising material must approved prior by the conference organizer)

Any financial funding at € 20,000 or above

Advertisement in programme

Major benefits:

- Inside front or back (no front or back cover)
- Full page advertisement: € 5,000
- Half page advertisement: € 3,000

Beverage patronage

Major benefits:

- Exclusive right to provide beverages during welcome reception, banquet dinner and conference breaks
- The nature of the particular patronage depends on the actual financial support

Exhibitions

To improve the conference's diversity, the ICC 2009 provides an integrated exhibition area close to technical sessions, coffee areas and poster areas to ensure frequent attendance. This is an excellent chance to present your company and its recent results, as well as to get in touch with other young and senior scientists from industry and academia. In addition, to provide you the best possible benefit, the exhibition areas will be grouped by topic.

The following exhibition booth dimensions are offered:

- 2m x 3m for €2,500
- 2m x 6m for €5,000
- 2m x 9m for €7,500
- 2m x 12m for €10,000

Each booth is equipped with a power supply. Any furniture or additional equipment requires to additional fees. The actual placement of the exhibition booth is determined by the conference organizer.

Additional Information

- Call for papers
- Technical Programme Committee, Organizers, Contact information



Committee:

- **General Chair:**
H. Akhavan, CEO, T-Mobile
- **Vice Chair:**
P. Kühn, University of Stuttgart
- **TPC Chair:**
G. Fettweis, TU Dresden
- **TPC Vice Chairs:**
W. Kabacinski, TU Poznan,
H. Stüttgen, NEC Europe
- **Tutorial Co-Chairs:**
A. Jajszczyk, AGH Cracow
M. Win (MIT)
- **Application Panels Co-Chairs:**
J. Eberspächer, TU Munich
S. Weinstein
- **Workshop Co-Chairs:**
K. David, University of Kassel
H. Yu, Huawei USA
- **Finance Co-Chairs:**
V. Schanz, VDE/ITG
B. Worthman, IEEE ComSoc
- **Local Organization:**
P. Rost, TU Dresden
P. Neu, VDE
- **ComSoc Project Manager:**
J. Leach-Barnaby

Important Dates:

Paper Submission: 8 Sep 2008
 Paper Acc. Notification: 15 Jan 2009
 Camera-Ready: 1 Mar 2009
 Tutorial Submission: 8 Sep 2008
 Workshop Proposals: 15 May 2008
 Panel Proposals: 1 Sep 2008
 Conference: 14-18 Jun 2009



Final Call for Papers

The IEEE Communications Society invites the world's leading researchers and engineers from academia, industry and government to exchange their ideas at the IEEE ICC 2009 conference in Dresden, Germany in June 2009. We invite you to submit your original papers on the most recent results and technology trends in the field of communications to one of the 11 symposia listed below. We also invite your suggestions for workshops, tutorials and industry panels on hot technology areas and business trends in the communications field.

For details please refer to the conference website and the schedule listed below.

1. Symposium on Selected Areas in Communications

Co-Chairs: Yacine Ghamri-Doudane, Gabriel Jakobson, Madjid Merabti, Sedat Oelcer

2. Communication Theory Symposium

Co-Chairs: Lutz Lampe, Aylin Yener, Angela Yingjun Zhang

3. Signal Processing for Communications Symposium

Co-Chairs: Luc Deneire, Tomohiko Taniguchi, Wai Pang Ng

4. Wireless Communications Symposium

Co-Chairs: Sonia Aissa, Nallanathan Arumugam, Erik Perrins, Yi Qian, Matthew Valenti, Takaya Yamazato

5. Wireless Networking Symposium

Co-Chairs: Yu Cheng, Hossam Hassanein, Mario Marchese, Abdelhamid Mellouk

6. Optical Networks and Systems Symposium

Co-Chairs: Dominic Schupke, Kyriakos Vlachos, Jun Zheng

7. Next Generation Networking Symposium

Co-Chairs: Mohammed Atiquzzaman, Marcus Brunner, Latif Latif, Ivica Rimac

8. Communications QoS, Reliability and Modelling Symposium

Co-Chairs: Nelson Fonseca, Ralf Lehnert, Hiromi Ueda

9. Adhoc and Sensor Networking Symposium

Co-Chairs: Tommaso Melodia, Hongchi Shi, Larry Xue, Mohamed Younis

10. Communications Software and Services Symposium

Co-Chairs: Wolfgang Kellerer, Pascal Lorenz, Giovanni Pau, Lars Wolf

11. Communication and Information Systems Security Symposium

Co-Chairs: Raouf Boutaba, Stefanos Gritzalis, Jiankun Hu, Peter Müller

TPC, Organizers, Contact

Overall organization

- **General Chair:**
H. Akhavan, CEO, T-Mobile
- **Vice Chair:**
P. Kühn, University of Stuttgart
- **Finance Chair:**
V. Schanz, VDE ITG,
ComSoc German Chapter
- **Finance Co-Chair:**
B. Worthman, IEEE ComSoc
- **Local Organization:**
P. Rost, TU Dresden,
P. Neu, VDE

Technical Program

- **TPC Chair:**
G. Fettweis, TU Dresden
- **TPC Vice Chairs:**
H. Stüttgen, NEC Europe Ltd.
W. Kabacinski, Poznan University
- **Tutorial Chair:**
A. Jajszczyk, AGH University, Krakow
M. Win, MIT
- **Application Session:**
S. Weinstein, Expert Panels
J. Eberspächer, TU Munich
- **Workshop Chair:**
K. David, University of Kassel
H. Yu, Huawei USA

Contact

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01069 Dresden, Germany